Materials Declaration Form

IPC	**1752**	**Version**	**2**
Form Type *	**Distribute**		
Sectionals *	**Material Info**	**Subsectionals ***	**A-D**
	Manufacturing Info	***: Required Field**	

Supplier Information			
Company Name *	**STMicroelectronics**	**Response Date ***	**2014-03-27**
Contact Name *	Refer to " Supplier Comment" section	**Contact Title**	Refer to " Supplier Comment" section
Contact Phone *	Refer to " Supplier Comment" section	**Contact Email ***	Refer to " Supplier Comment" section
Authorized Representative *	**Giovanni Giacopello**	**Representative Title**	**AMS & IPD Materials Declaration Champion**
Representative Phone *	Refer to " Supplier Comment" section	**Representative Email ***	Refer to " Supplier Comment" section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/online_tech_support.html		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	**true**	**Legal Declaration ***	**Standard**

Legal Statement	Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as omprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Signature Not Verified

Digitally signed by Giovanni Giacopello
Date: 2014.03.27 09:23:26 +01:00

Product				
Mfr Item Number	**Mfr Item Name**	**Version**	**Mfr Site**	**Date**
	KKQB*F922AR6	A	SH1A	2014-03-27
	Amount	**UoM**	**Unit type**	**ST ECOPACK Grade**
	3.26	mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL Rating	**Classification Temp**	**Nbr of Reflow Cycles**		
NAC	260	3		
bulk Solder Termination	**Terminal Plating**	**Terminal Base Alloy**	**Comment**	
Tin/Silver/Copper (SAC305)	Tin/Silver/Copper (Sn/Ag/Cu)	NAC		

Package Designator	**Size**	**Nbr of instances**	**Shape**	
WAFER	2.04 - 1.4 - 0.35	8	No lead	
Comment	Package: CSPS0.5 7-10; MDF valid for TS922EIJT			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	**Response**
Product(s) meets EU RoHS requirement without any exemptions	**true**
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false

Exemption Id.	**Description**

QueryList : REACH-16th December 2013				
Query				**Response**
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				**true**
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	KKQB*F922AR6					
Homogeneous Material	**Material Group**	**Mass**	**UoM**	**Level**	**Substance Category**	**Substance**	**CAS**	**Exempt**	**Mass**	**UoM**	**Concentration in homogeneous material (ppm)**	**Concentration in product (ppm)**
die (s)	Other inorganic materials	2.387	mg	supplier	die	Silicon (Si)	7440-21-3		2.194	mg	919145	548500
die (s)				supplier	metallization	Aluminium (Al)	7429-90-5		0.008	mg	3351	2000
die (s)				supplier	passivation	Silicon Nitride (SiN)	68034-42-4		0.004	mg	1676	1000
die (s)				supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0.031	mg	12987	7750
die (s)				supplier	UBM	Copper (Cu)	7440-50-8		0.003	mg	1257	750
die (s)				supplier	UBM	Titanium (Ti)	7440-32-6		0.002	mg	838	500
die (s)				supplier	UBM	Gold (Au)	7440-57-5		0.003	mg	1257	750
die (s)				supplier	UBM	Nickel (Ni)	7440-02-0		0.013	mg	5446	3250
die (s)				supplier	Coating	Polyethylene terephthalate	25038-59-9		0.053	mg	22204	13250
die (s)				supplier	Coating	Silica, vitreous	60676-86-0		0.053	mg	22204	13250
die (s)				supplier	Coating	Epoxy resin	Proprietary		0.01	mg	4189	2500
die (s)				supplier	Coating	Acrylic polymer	9003-01-4		0.01	mg	4189	2500
die (s)				supplier	Coating	Carbon black	1333-86-4		0.003	mg	1257	750
BUMPS	Solder	0.873	mg	supplier	bump	Tin (Sn)	7440-31-5		0.843	mg	965636	210750
BUMPS				supplier	bump	Silver (Ag)	7440-22-4		0.026	mg	29782	6500
BUMPS				supplier	bump	Copper (Cu)	7440-50-8		0.004	mg	4582	1000